RoHS

COMPLIANT



Vishay Semiconductors

HEXFRED® Ultrafast Soft Recovery Diode, 60 A



SOT-227

PRODUCT SUMMARY						
V_{R}	600 V					
V _F (typical) at 125 °C	1.4 V					
Q _{rr} (typical)	270 nC					
I _{RRM} (typical)	7.0 A					
t _{rr} (typical)	65 ns					
dl _{(rec)M} /dt (typical) at 125 °C	270 A/μs					
I _{F(DC)} at T _C	40 A at 100 °C					
Package	SOT-227					
Circuit configuration	Two separate diodes					

FEATURES

- Fast recovery time characteristic
- · Electrically isolated base plate
- Large creepage distance between terminal
- · Simplified mechanical designs, rapid assembly
- UL approved file E78996
- Designed for industrial level
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION

This SOT-227 modules with HEXFRED® rectifier are available in two basic configurations. They are the antiparallel and the parallel configurations. The antiparallel configuration (VS-HFA120EA60) is used for simple series rectifier and high voltage application. The parallel configuration (VS-HFA120FA60) is used for simple parallel rectifier and high current application. The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built. These modules are intended for general applications such as power supplies, battery chargers, electronic welders, motor control, DC chopper, and inverters.

ABSOLUTE MAXIMUM RATINGS PER LEG					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Cathode to anode voltage	V_R		600	V	
Continuous forward current	I _F	T _C = 25 °C	75		
		T _C = 100 °C	40	Α	
Single pulse forward current	I _{FSM}	T _J = 25 °C	800		
Maximum repetitive forward current	I _{FRM}	Rated V_R , square wave, 20 kHz, $T_C = 60 ^{\circ}C$	180		
RMS isolation voltage, any terminal to case	V _{ISOL}	t = 1 minute	2500	V	
Maximum power dissipation	P _D	T _C = 25 °C	180	W	
		T _C = 100 °C	71		
Operating junction and storage temperature range	T _J , T _{Stg}		- 55 to 150	°C	

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	I _R = 100 μA		600	-	-	
Maximum forward voltage V _{FM}		I _F = 60 A	See fig. 1	-	1.5	1.7	V
	V_{FM}	I _F = 120 A		-	1.9	2.1	
		I _F = 60 A, T _J = 125 °C		-	1.4	1.6	
Maximum reverse leakage current I _{RM}		V _R = V _R rated	Coo fig. 0	-	2.5	20	
	IRM	T _J = 125 °C, V _R = 0.8 x V _R rated	See fig. 2	-	130	2000	μA
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	120	170	pF

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DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A}$	Vμs, V _R = 30 V	-	34	-	ns
Reverse recovery time See fig. 5, 6 and 16	t _{rr1}	T _J = 25 °C		-	65	98	
coo ng. o, o and ro	t _{rr2}	T _J = 125 °C		-	130	200	
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	7.0	13	А
See fig. 7 and 8	I _{RRM2}	T _J = 125 °C	$I_F = 60 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	13	23	
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	270	410	nC
See fig. 9 and 10	Q _{rr2}	T _J = 125 °C		-	490	740	110
Peak rate of recovery current during t _b	dI _{(rec)M} /dt1	T _J = 25 °C		-	350	-	Δ /
See fig. 11 and 12	e fig. 11 and 12 $dl_{(rec)M}/dt2 T_J = 125 \text{ °C}$		-	270	-	- A/μs	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	В		-	-	0.70	
Junction to case, both legs conducting	- R _{thJC}		-	-	0.35	°C/W
Case to heatsink	R _{thCS}	Flat, greased surface	-	0.05	-	
Weight			-	30	-	g
Mounting torque			-	-	1.3	Nm
Case style			SOT-227			



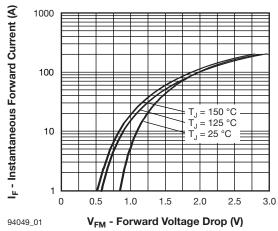


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

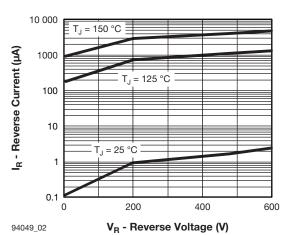


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

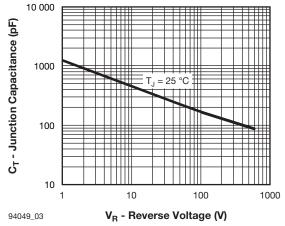


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

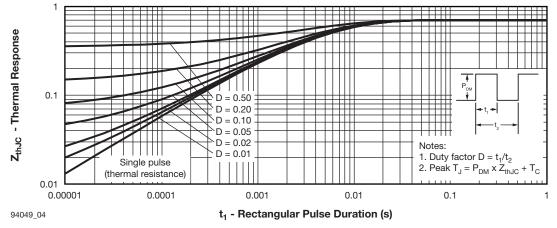


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)





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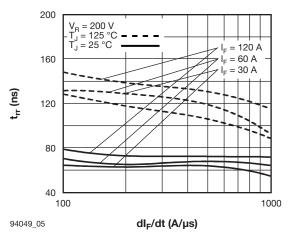


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

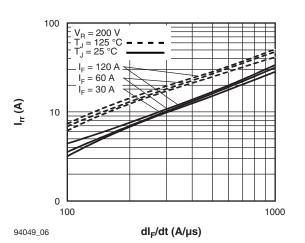


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

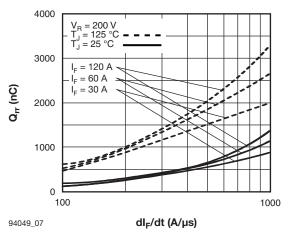


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

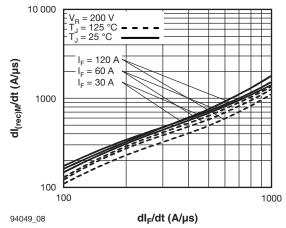


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)

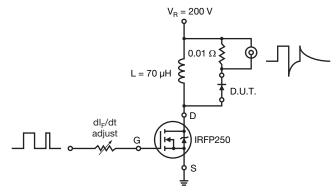
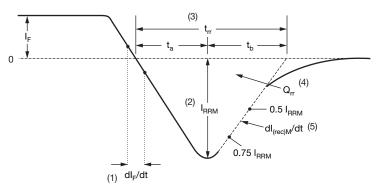


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (4) $\rm Q_{rr}$ area under curve defined by $\rm t_{rr}$ and $\rm I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) dI_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

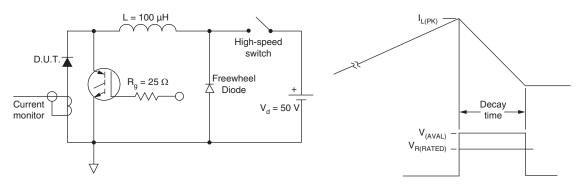
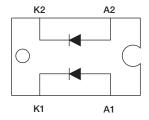


Fig. 11 - Avalanche Test Circuit and Waveforms

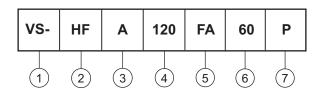


CIRCUIT CONFIGURATION



ORDERING INFORMATION TABLE

Device code



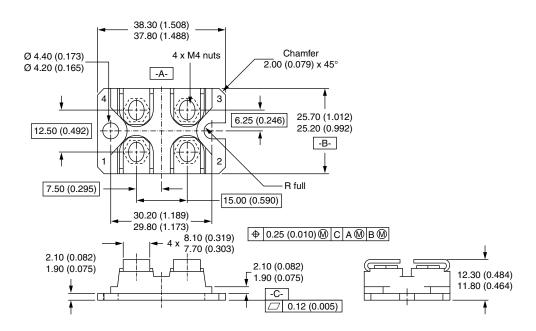
- 1 Vishay Semiconductors product
- 2 HEXFRED® family
- 3 Process: A electron irradiated
- Current rating (120 = 120 A)
- 5 Package indicator (SOT-227)
- 6 Voltage rating (60 = 600 V)
- 7 P = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95036			
Packaging information	www.vishay.com/doc?95037			



SOT-227

DIMENSIONS in millimeters (inches)



Notes

- Dimensioning and tolerancing per ANSI Y14.5M-1982
- · Controlling dimension: millimeter

Document Number: 95036 Revision: 28-Aug-07

Legal Disclaimer Notice



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